



# Product Change Notification

**Change Notification #:** 116094 - 00  
**Change Title:** Intel® Server Chassis P4304XXMUXX, and Intel® Server Chassis P4304XXMFEN2 PCN 116094-00, Product Design, Addition of Gaskets for PCIe Brackets  
**Date of Publication:** February 14, 2018

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material: *</b>	March 2, 2018
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is adding gaskets on the PCIe brackets of the Intel® Server Chassis P4304XXMFEN2 and Intel® Server Chassis P4304XXMUXX, to improve the grounding for the add-in cards in order to increase the electro static discharge (ESD) damage prevention (from 4kV up to 8kV).



Figure 1. Gaskets to add to the Brackets



Figure 2. PCIe brackets with new Gaskets Attached

**Customer Impact of Change and Recommended Action:**

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

**Products Affected / Intel Ordering Codes:**

Product Code	MM#	Pre Change TA	Post Change TA
P4304XXMFEN2	936416	H24211-007	H24211-008
P4304XXMUXX	937011	H45587-004	H45587-005

**PCN Revision History:**

**Date of Revision:**  
February 14, 2018

**Revision Number:**  
00

**Reason:**  
Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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